

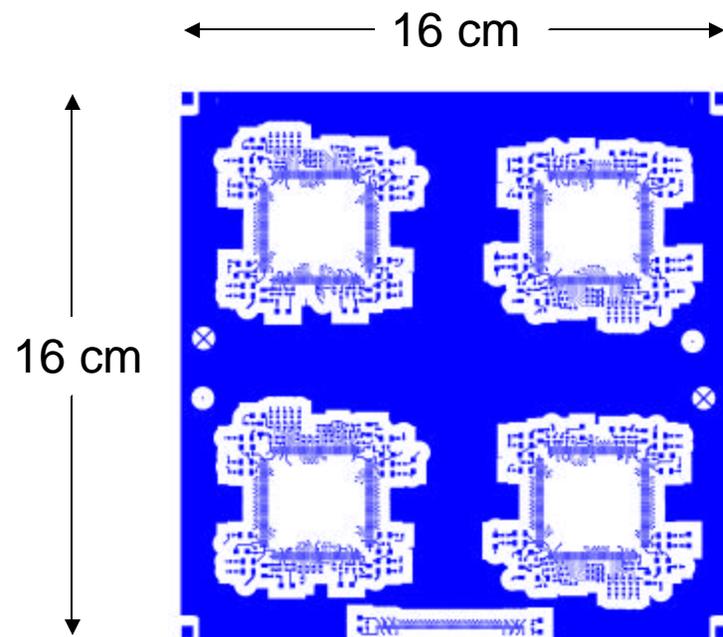
# Status of DCAL Front End Electronics

Tim Cundiff

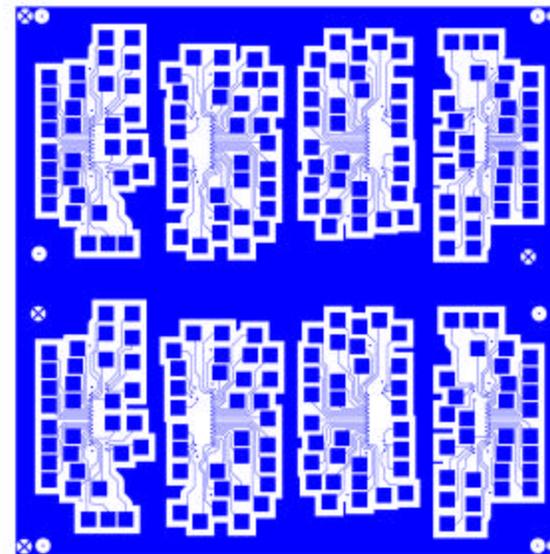
Gary Drake

Mar. 23, 2007

# Layout of Front End Board

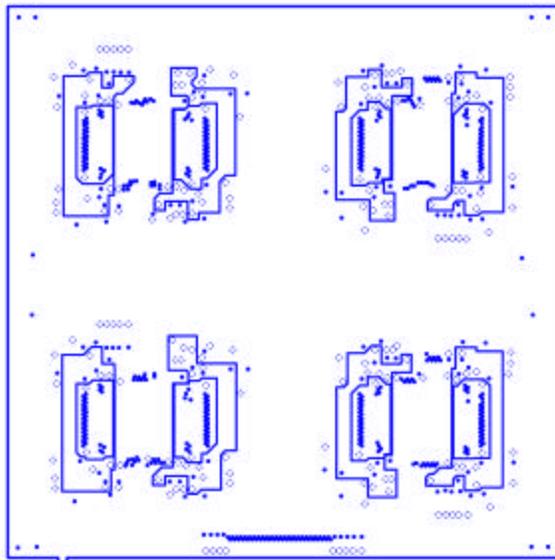


Top Side

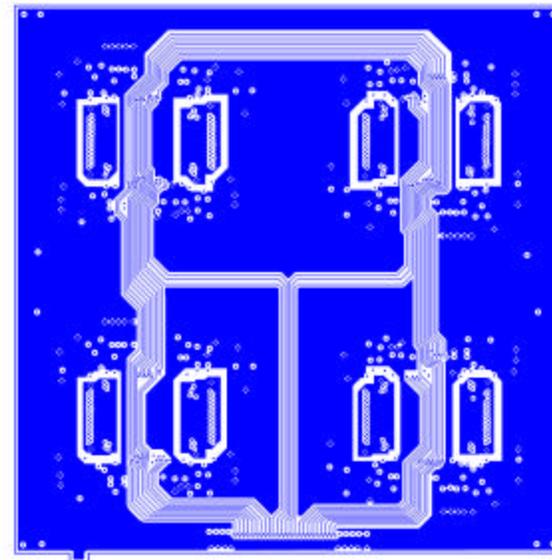


Bottom Side  
(Glue Pads & Traces))

# Layout of Front End Board



Power Plane

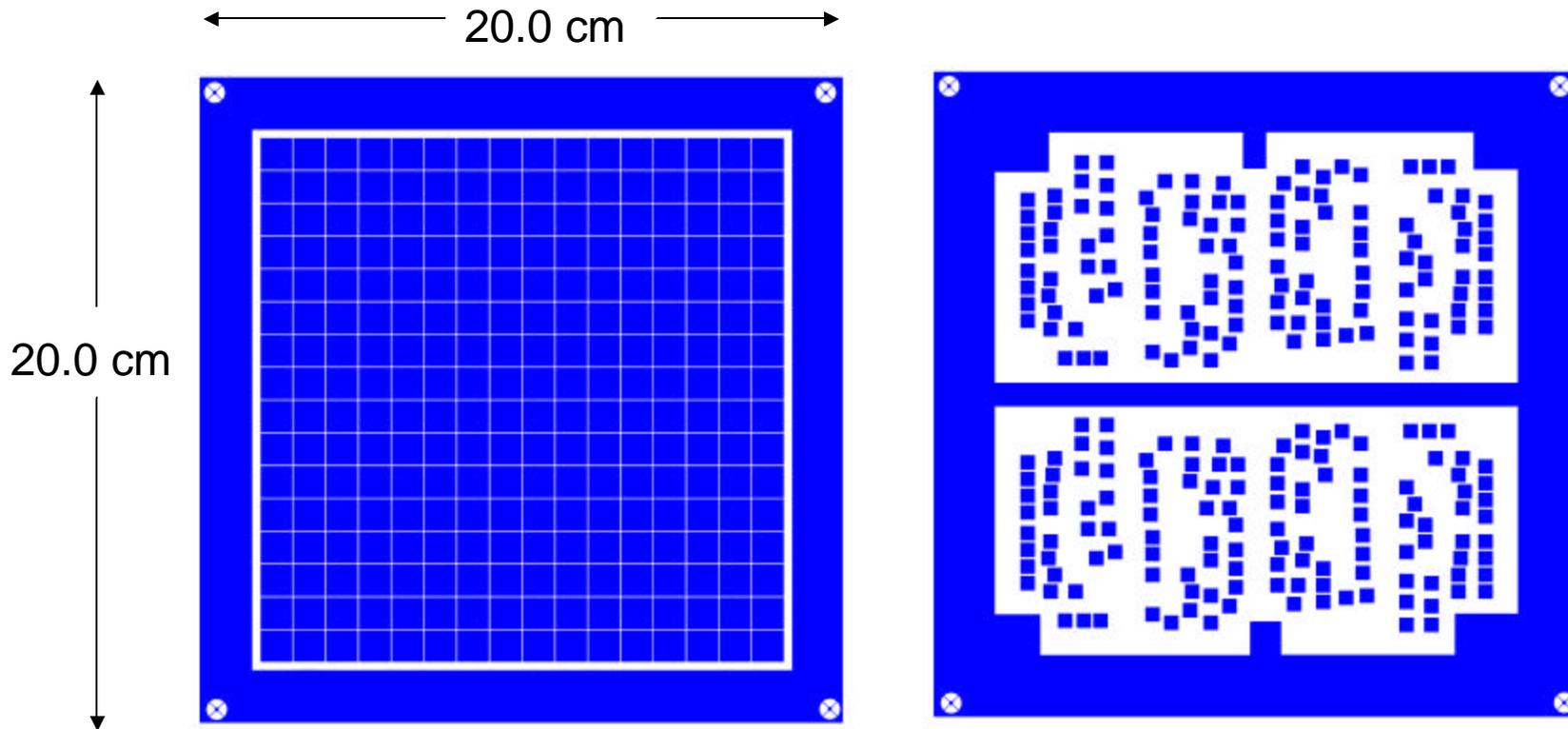


Digital Trace Layer

Board has 8 Layers, 3 Layers with Blind Vias.

Status: Board is being Fabricated. Due 3/28/07.

# RPC Pad Board

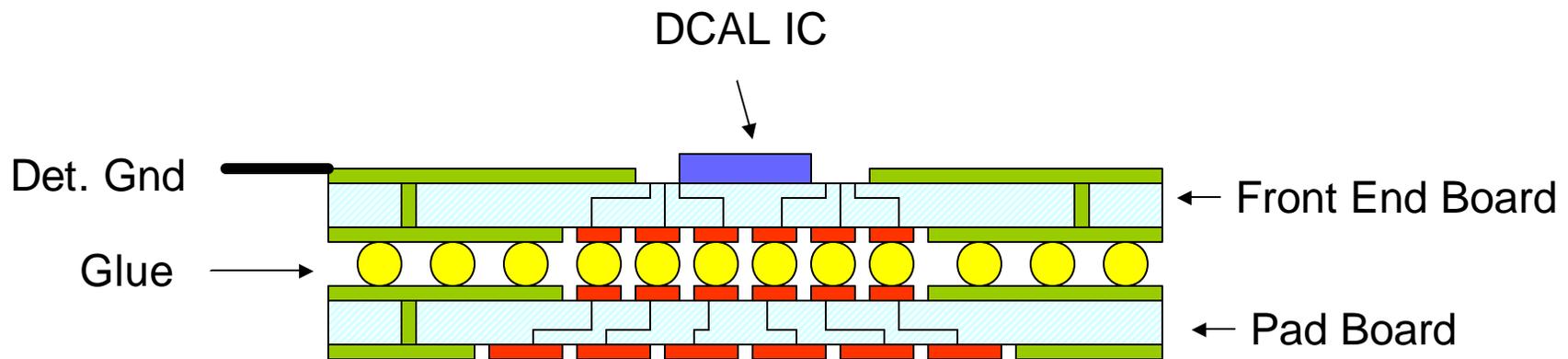


Bottom Side  
(Chamber Pads)

Top Side  
(Glue Pads)

16 cm X 16 cm Active Area Centered in Middle  
Detector Ground around Edges, Top & Bottom

# Detector Ground in the PCBs

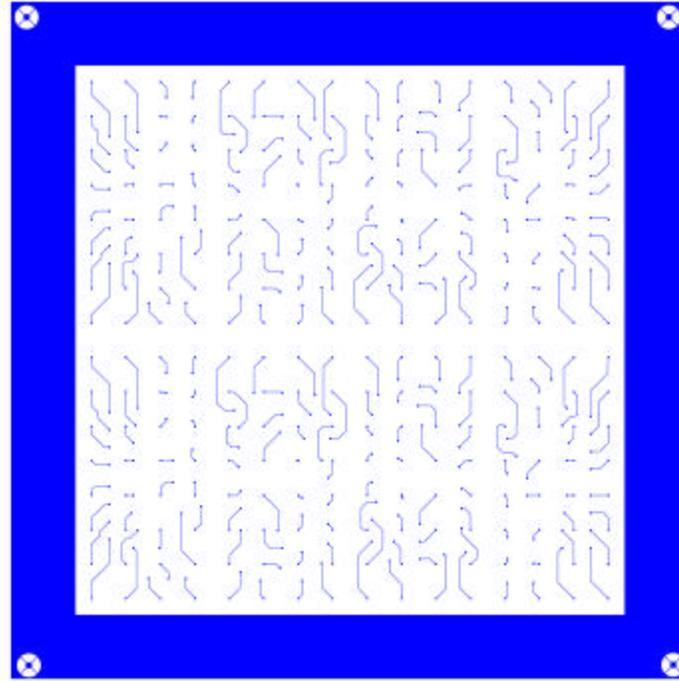


Detector GND (Signal Return) is Carried From Pad Board to DCAL IC.

Presently, FEB has Outer Rim for this Connection, with Glue Spots.

This Will Not be So in the Future...

# RPC Pad Board

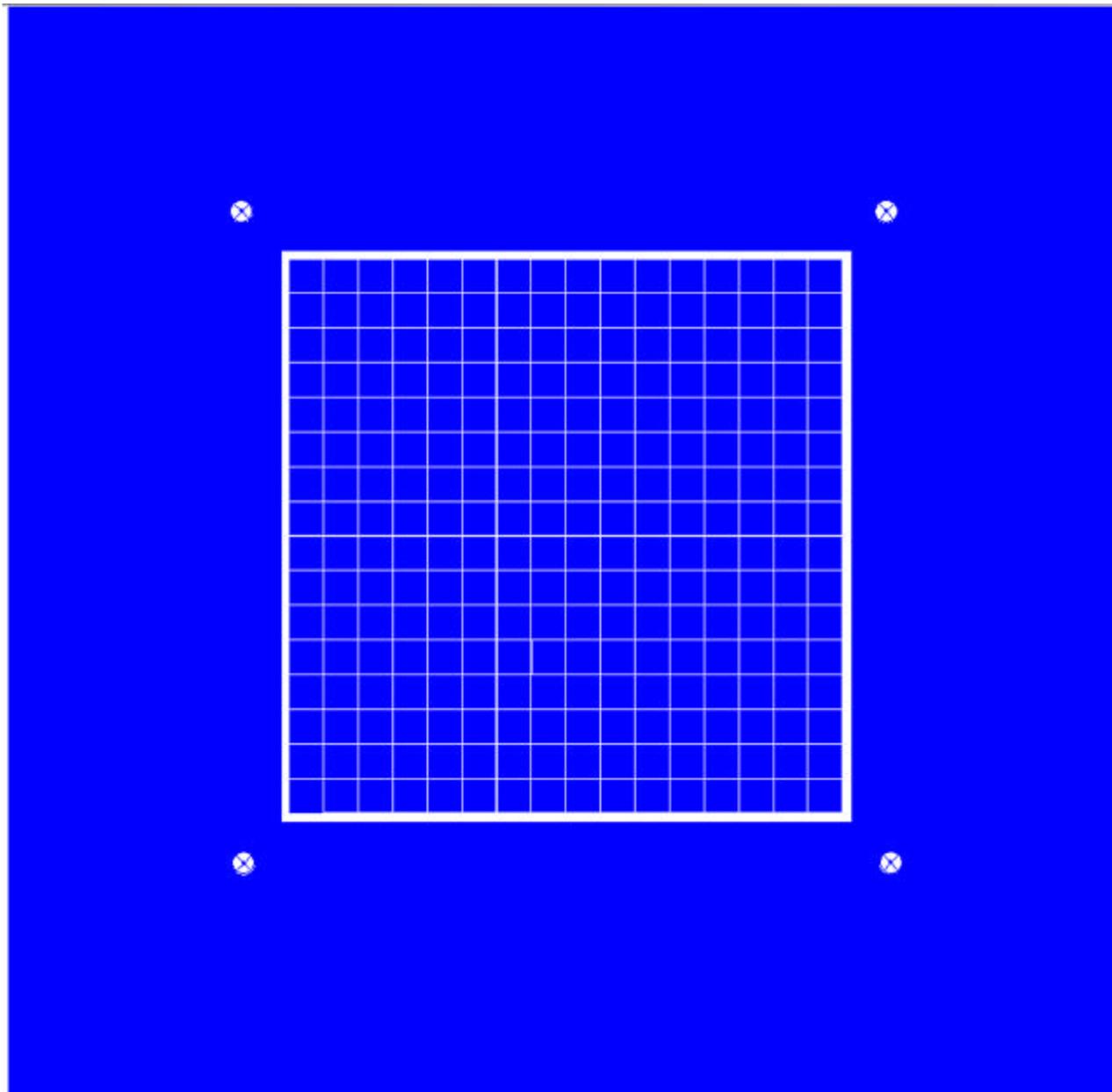


Internal Trace Layer

Board has 4 Layers, 2 Layers with Blind Vias.

Status: Board will begin Fabrication 3/26/07, 10 day.

GEM  
Pad  
Board



323.85 mm  
(12.75")

# Overall Status

- Front End Boards being Fabricated, due 3/28/07
- Data Concentrators Arrived! 1 Assembled, Awaiting Testing
- FEB Test PC Interface being Fabricated, due 3/27/07
- DCON Test PC Interface being Fabricated, due 4/3/07
- RPC Pad Board Layout Done, Begin Fab 3/26/07
- GEM Pad Board Layout Done, Begin Fab ???